

SYSTEM AND METHOD FOR SELF-LEVELING
HEAT SINK FOR MULTIPLE HEIGHT DEVICES

ABSTRACT OF THE DISCLOSURE

A self-leveling heat sink includes a spring-arm device having at least one aperture and at least one spring-arm is coupled to a substrate. The substrate has at least one package mounted thereon, so that when the spring-arm device is mounted to the substrate the at least one package passes through the at least one aperture. A heat sink operable to remove heat from the at least one package has at least one heat sink post operable to receive a heat sink clip located at the distal end of each of the at least one spring-arms. Each of the at least one spring-arms extending from an inside edge of the at least one aperture and operable to couple the heat sink to the at least one package.